

REVISIONS

LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
A	Added vendor CAGE 27014. Added case outline G. Added device type 02.	94-07-21	M.A. FRYE
B	Updated boilerplate. Added case outline P. Added delta table for device class V.	97-08-27	R. MONNIN
C	Changes to test conditions for I _{IO} , I _{IB} , V _{ICR} , and I _{OH} in table I. - rrp	97-11-18	R. MONNIN
D	Make change to θ_{JA} limit for case P as specified under 1.3. - ro	98-01-21	R. MONNIN
E	Replaced reference to MIL-STD-973 with reference to MIL-PRF-38535. - gt	04-01-29	R. MONNIN
F	Add radiation hardened requirements for device type 02. Add paragraphs 1.5, 3.2.3, and 4.4.4.1. Add two footnotes to Table I. Make changes to Table IIA. - ro	07-05-09	R. HEBER
G	Add device type 03 tested at Low Dose Rate. Make changes to 1.2.2, 1.5, table I, figure 1, table IIB, and 4.4.4.1. -rrp	07-10-31	R. HEBER
H	Add appendix A, die requirements. - drw	09-04-17	Joseph D. Rodenbeck
J	Update document paragraphs to current MIL-PRF-38535 requirements. - ro	16-01-28	C. SAFFLE



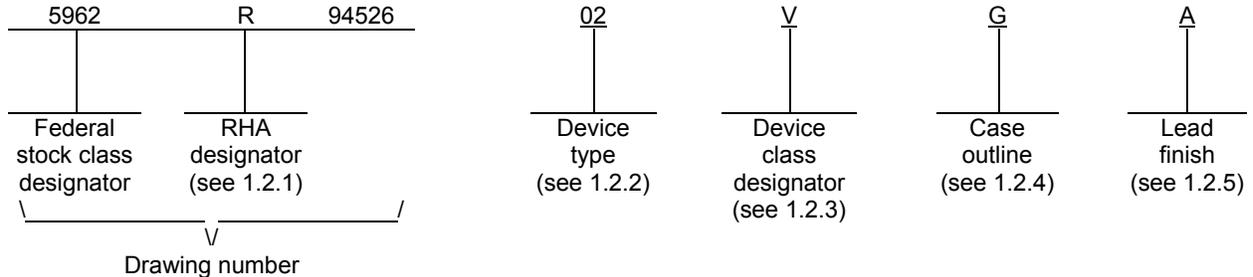
THE ORIGINAL FIRST SHEET OF THIS DRAWING HAS BEEN REPLACED.

REV																			
SHEET																			
REV	J	J	J																
SHEET	15	16	17																
REV STATUS OF SHEETS	REV			J	J	J	J	J	J	J	J	J	J	J	J	J	J	J	J
	SHEET			1	2	3	4	5	6	7	8	9	10	11	12	13	14	14	
PMIC N/A	PREPARED BY Rick C. Officer					<p align="center">DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990 http://www.landandmaritime.dla.mil</p> <p align="center">MICROCIRCUIT, LINEAR, DUAL DIFFERENTIAL COMPARATOR, MONOLITHIC SILICON</p>													
<p align="center">STANDARD MICROCIRCUIT DRAWING</p> <p align="center">THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE</p>	CHECKED BY Sandra B. Rooney																		
	APPROVED BY Michael A. Frye																		
	DRAWING APPROVAL DATE 94-02-09																		
AMSC N/A	REVISION LEVEL J					SIZE A	CAGE CODE 67268	5962-94526											
						SHEET		1 OF 17											

1. SCOPE

1.1 Scope. This drawing documents two product assurance class levels consisting of high reliability (device class Q and M) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels is reflected in the PIN.

1.2 PIN. The PIN is as shown in the following example:



1.2.1 RHA designator. Device classes Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. Device class M RHA marked devices meet the MIL-PRF-38535, appendix A specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 Device type(s). The device type(s) identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	LM193	Dual differential comparator
02	LM193A	Dual differential comparator
03	LM193A	Dual differential comparator

1.2.3 Device class designator. The device class designator is a single letter identifying the product assurance level as follows:

<u>Device class</u>	<u>Device requirements documentation</u>
M	Vendor self-certification to the requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A
Q or V	Certification and qualification to MIL-PRF-38535

1.2.4 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
G	MACY1-X8	8	Can
P	GDIP1-T8 or CDIP2-T8	8	Dual-in-line
2	CQCC1-N20	20	Square leadless chip carrier

1.2.5 Lead finish. The lead finish is as specified in MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

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1.3 Absolute maximum ratings. 1/

Supply voltage (V _{CC})	36 V
Differential input voltage	±36 V
Input voltage range (either input)	-0.3 V to 36 V
Output voltage (V _{OUT})	36 V
Output current (I _{OUT})	20 mA
Duration of output short-circuit to ground	Unlimited
Continuous total power dissipation (P _D) (T _A ≤ 25°C):	
Case G	660 mW
Case P	780 mW <u>2/</u>
Case 2	900 mW <u>2/</u>
Storage temperature range	-65°C to +150°C
Case temperature for 60 seconds (case 2)	260°C
Case temperature for 10 seconds (cases G and P)	260°C
Thermal resistance, junction-to-case (θ _{JC}):	
Case G	44°C/W
Case P	33°C/W
Case 2	20°C/W
Thermal resistance, junction-to-ambient (θ _{JA}):	
Case G	174°C/W still air
	99°C/W 500 LFPM
Case P	180°C/W still air
	85°C/W 500 LFPM
Case 2	65°C/W

1.4 Recommended operating conditions.

Supply voltage (V _{CC})	5 V
Operating ambient temperature range (T _A)	-55°C to +125°C

1.5 Radiation features. 3/

Maximum total dose available (dose rate = 50 – 300 rad(Si)/s):	
Device class V (device type 02)	100 krad(Si)
Maximum total dose available (dose rate = 10 mrad(Si)/s):	
Device class V (device type 03)	100 krad(Si)

The manufacturer supplying RHA parts on this drawing has performed a characterization test to demonstrate that the parts do not exhibit enhanced low dose rate sensitivity (ELDRS) according to MIL-STD-883 method 1019 paragraph 3.13.1.1. Therefore this part may be considered ELDRS free. However, the manufacturer will continue to perform low dose rate lot acceptance testing on each wafer lot or wafer until characterization testing has been performed according to method 1019 of MIL-STD-883. Since the redesigned part did not demonstrate ELDRS per method 1019 and the previously tested device was ELDRS, device type 03 will be added to distinguish it from the 02 device.

- 1/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.
- 2/ For case P, with T_A > +68°C, derating at 8.4 mW/°C. For case 2, with T_A > +68°C, derating at 11.0 mW/°C.
- 3/ For device type 02, this part may be dose rate sensitive in a space environment and may demonstrate enhanced low dose rate effects. Radiation end point limits for the noted parameters are guaranteed only for the conditions as specified in MIL-STD-883, method 1019, condition A. For device type 03, this part has been tested and does not demonstrate low dose rate sensitivity. Radiation end point limits for the noted parameters are guaranteed for the conditions specified in MIL-STD-883, method 1019, condition D.

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2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.
MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.
MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <http://quicksearch.dla.mil> or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 as specified herein, or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. The individual item requirements for device class M shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein.

3.1.1 Microcircuit die. For the requirements of microcircuit die, see appendix A to this document.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V or MIL-PRF-38535, appendix A and herein for device class M.

3.2.1 Case outlines. The case outlines shall be in accordance with 1.2.4 herein.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.3 Radiation exposure circuit. The radiation exposure circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing and acquiring activity upon request.

3.3 Electrical performance characteristics and postirradiation parameter limits. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table IIA. The electrical tests for each subgroup are defined in table I.

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TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions <u>1/ 2/</u> -55°C ≤ T _A ≤ +125°C V _{CC} = 5 V unless otherwise specified	Group A subgroups	Device type	Limits <u>3/</u>		Unit
					Min	Max	
Input offset voltage	V _{IO}	V _{CC} = 5 V to 30 V, V _{IC} = V _{IC} min, V _{OUT} = 1.4 V	1	01		5	mV
			2, 3			9	
		V _{CC} = 5 V to 30 V, V _{CM} = 0 V	1	02, 03		2	
			2, 3			4	
		V _{CC} = 30 V, T _A = 25°C, V _{CM} = 28.5 V	1			2	
V _{CC} = 30 V, V _{CM} = 28 V	2, 3			4			
Input offset current	I _{IO}	V _{OUT} = 1.4 V	1	01		25	nA
			2, 3			100	
		V _{OUT} = 1.5 V, R _S = 50 Ω, V _{CM} = 0 V	1	02, 03		25	
			2, 3			100	
Input bias current	I _{IB}	V _{OUT} = 1.4 V	1	01		-100	nA
			2, 3			-300	
		V _{OUT} = 1.5 V, V _{CM} = 0 V	1	02, 03		-100	
			2, 3			-300	
Common mode input voltage range	V _{ICR}	<u>4/ 5/</u>	1	01	0 to V _{CC} -1.5		V
			2, 3			0 to V _{CC} -2	
		V _{CC} = 30 V <u>4/ 5/</u>	1	02, 03	0 to V _{CC} -1.5		
			2, 3			0 to V _{CC} -2	
High level output current	I _{OH}	V _{OH} = 30 V, V _{ID} = 1 V, T _A = +125°C, -55°C	2, 3	01		1	μA
			1			0.65	
		V _{OH} = 30 V, V _{ID} = 1 V, V _{CC} = 30 V	2, 3	02, 03		1	
Low level output current	I _{OL}	V _{OL} = 1.5 V, V _{ID} = 1 V	1	01, 02, 03	6		mA
			2, 3	02, 03	4		
Low level output voltage	V _{OL}	I _{OL} = 4 mA, V _{ID} = -1 mA	1	01, 02, 03		400	mV
			2, 3			700	

See footnotes at end of table.

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TABLE I. Electrical performance characteristics – Continued.

Test	Symbol	Conditions <u>1/ 2/</u> -55°C ≤ T _A ≤ +125°C V _{CC} = 5 V unless otherwise specified	Group A subgroups	Device type	Limits <u>3/</u>		Unit
					Min	Max	
Supply current	I _{CC}	V _{CC} = 5 V, R _L = ∞, T _A = +25°C	1	01,02, 03		1	mA
		V _{CC} = 30 V, R _L = ∞	2, 3	01		2.5	
		V _{CC} = 36 V	1, 2, 3	02, 03		2.5	
Power supply rejection ratio	PSRR	V _{CC} = 5 V to 30 V, R _S = 50 Ω, T _A = +25°C	1	02, 03	60		dB
Common mode rejection ratio	CMRR	V _{CC} = 30 V, T _A = +25°C, V _{CM} = 0 V to 28.5 V, R _S = 50 Ω,	1	02, 03	60		dB
Differential input voltage	V _{DIFF}	V _{CC} = 30 V, V _{IN} = 0 V to ±36 V	1, 2, 3	02, 03		500	nA
Large signal differential voltage amplification	A _{VD}	V _{CC} = 15 V, T _A = +25°C, V _{OUT} = 1.4 V to 11.4 V, R _L ≥ 15 kΩ to V _{CC}	4	01	50		V/mV
		V _{CC} = 15 V, R _L = 15 kΩ, V _{OUT} = 1 V to 11 V	4 5, 6	02, 03	50 25		
Response time low to high	t _{RLH}	V _{OD} = 5 mV, V _{CC} = 5 V, T _A = +25°C	9	02, 03	5.0		μs
		V _{OD} = 50 mV, V _{CC} = 5 V, T _A = +25°C			0.8		
		M,D,P,L,R	9	02, 03		1.0	
Response time high to low	t _{RHL}	V _{OD} = 5 mV, V _{CC} = 5 V, T _A = +25°C	9	02, 03	2.5		μs
		V _{OD} = 50 mV, V _{CC} = 5 V, T _A = +25°C			0.8		

- 1/ Devices supplied to this drawing are tested through all levels M, D, P, L, R of irradiation. Pre and Post irradiation values are identical unless otherwise specified in Table I. When performing post irradiation electrical measurements for any RHA level, T_A = +25°C.
- 2/ For device type 02, this part may be dose rate sensitive in a space environment and may demonstrate enhanced low dose rate effects. Radiation end point limits for the noted parameters are guaranteed only for the conditions as specified in MIL-STD-883, method 1019, condition A. For device type 03, this part has been tested and does not demonstrate low dose rate sensitivity. Radiation end point limits for the noted parameters are guaranteed for the conditions specified in MIL-STD-883, method 1019, condition D.
- 3/ The term "min" (minimum) and "max" (maximum) shall be considered to apply to magnitudes only. Negative current shall be defined as conventional current flow out of a device terminal.
- 4/ The voltage at either input or common-mode should not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is +V_{CC} - 1.5, but either or both inputs can go to 30 V without damage.
- 5/ Guaranteed by V_{IO} test.

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Device types	01	01, 02, 03	02, 03
Case outlines	2	P	G
Terminal number	Terminal symbol		
1	NC	OUTPUT 1	OUTPUT 1
2	OUTPUT 1	-INPUT 1	-INPUT 1
3	NC	+INPUT 1	+INPUT 1
4	NC	GROUND	GROUND
5	-INPUT 1	+INPUT 2	+INPUT 2
6	NC	-INPUT 2	-INPUT 2
7	+INPUT 1	OUTPUT 2	OUTPUT 2
8	NC	V _{CC}	V _{CC}
9	NC	---	---
10	GROUND	---	---
11	NC	---	---
12	+INPUT 2	---	---
13	NC	---	---
14	NC	---	---
15	-INPUT 2	---	---
16	NC	---	---
17	OUTPUT 2	---	---
18	NC	---	---
19	NC	---	---
20	V _{CC}	---	---

NC = No connection

FIGURE 1. Terminal connections.

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3.5 Marking. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535. Marking for device class M shall be in accordance with MIL-PRF-38535, appendix A.

3.5.1 Certification/compliance mark. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535. The compliance mark for device class M shall be a "C" as required in MIL-PRF-38535, appendix A.

3.6 Certificate of compliance. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6.2 herein). The certificate of compliance submitted to DLA Land and Maritime-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein or for device class M, the requirements of MIL-PRF-38535, appendix A and herein.

3.7 Certificate of conformance. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 or for device class M in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

3.8 Notification of change for device class M. For device class M, notification to DLA Land and Maritime-VA of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change that affects this drawing.

3.9 Verification and review for device class M. For device class M, DLA Land and Maritime, DLA Land and Maritime's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

3.10 Microcircuit group assignment for device class M. Device class M devices covered by this drawing shall be in microcircuit group number 50 (see MIL-PRF-38535, appendix A).

4. VERIFICATION

4.1 Sampling and inspection. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. For device class M, sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

4.2 Screening. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection.

4.2.1 Additional criteria for device class M.

a. Burn-in test, method 1015 of MIL-STD-883.

(1) Test condition B or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.

(2) $T_A = +125^{\circ}\text{C}$, minimum.

b. Interim and final electrical test parameters shall be as specified in table IIA herein.

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TABLE IIA. Electrical test requirements.

Test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)	Subgroups (in accordance with MIL-PRF-38535, table III)	
	Device class M	Device class Q	Device class V
Interim electrical parameters (see 4.2)	---	---	---
Final electrical parameters (see 4.2)	1,2,3,4,5,6,9 <u>1/</u>	1,2,3,4, <u>1/</u> 5,6,9	1,2,3,4, <u>1/</u> 5,6,9
Group A test requirements (see 4.4)	1,2,3,4,5,6,9	1,2,3,4,5,6,9	1,2,3,4,5,6,9
Group C end-point electrical parameters (see 4.4)	1	1	1 <u>2/</u>
Group D end-point electrical parameters (see 4.4)	1	1	1
Group E end-point electrical parameters (see 4.4)	1,4,9	1,4,9	1,4,9

1/ PDA applies to subgroup 1.

2/ Delta limits as specified in table IIB shall be required where specified, and the delta limits shall be computed with reference to the previous endpoint electrical parameters.

TABLE IIB. Delta limits at +25°C.

Parameter	Device types	Limit
V _{IO}	02, 03	+1 mV
I _B	02, 03	+15 nA

4.2.2 Additional criteria for device classes Q and V.

- a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
- b. Interim and final electrical test parameters shall be as specified in table IIA herein.
- c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.

4.3 Qualification inspection for device classes Q and V. Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

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4.4 Conformance inspection. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections, and as specified herein. Quality conformance inspection for device class M shall be in accordance with MIL-PRF-38535, appendix A and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4.1 Group A inspection.

- a. Tests shall be as specified in table IIA herein.
- b. Subgroups 7, 8, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.

4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:

- a. Test condition B or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
- b. $T_A = +125^\circ\text{C}$, minimum.
- c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.

4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.4 Group E inspection. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).

- a. End-point electrical parameters shall be as specified in table IIA herein.
- b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535, appendix A for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at $T_A = +25^\circ\text{C} \pm 5^\circ\text{C}$, after exposure, to the subgroups specified in table IIA herein.

4.4.4.1 Total dose irradiation testing. Total dose irradiation testing shall be performed in accordance with MIL-STD-883 method 1019 condition A for device type 02, condition D for device type 03 and as specified herein.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

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6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor prepared specification or drawing.

6.1.2 Substitutability. Device class Q devices will replace device class M devices.

6.2 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

6.3 Record of users. Military and industrial users should inform DLA Land and Maritime when a system application requires configuration control and which SMD's are applicable to that system. DLA Land and Maritime will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DLA Land and Maritime-VA, telephone (614) 692-8108.

6.4 Comments. Comments on this drawing should be directed to DLA Land and Maritime-VA, Columbus, Ohio 43218-3990, or telephone (614) 692-0540.

6.5 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

6.6 Sources of supply.

6.6.1 Sources of supply for device classes Q and V. Sources of supply for device classes Q and V are listed in MIL-HDBK-103 and QML-38535. The vendors listed in MIL-HDBK-103 and QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DLA Land and Maritime-VA and have agreed to this drawing.

6.6.2 Approved sources of supply for device class M. Approved sources of supply for class M are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DLA Land and Maritime-VA.

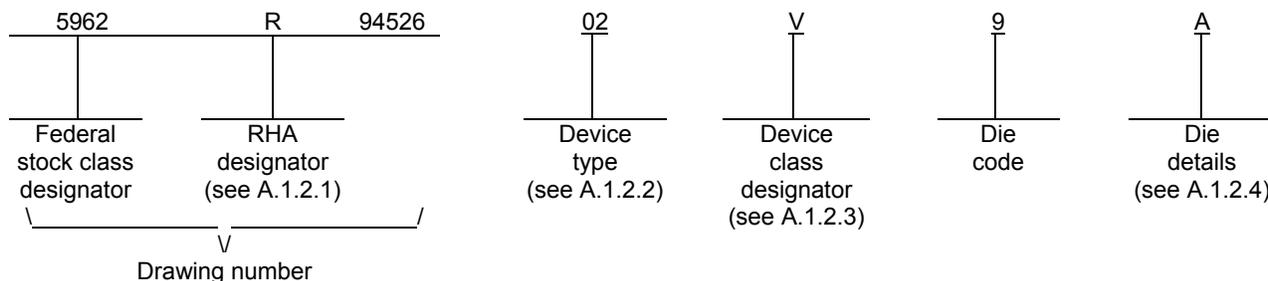
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A.1 SCOPE

A.1.1 Scope. This appendix establishes minimum requirements for microcircuit die to be supplied under the Qualified Manufacturers List (QML) Program. QML microcircuit die meeting the requirements of MIL-PRF-38535 and the manufacturers approved QM plan for use in monolithic microcircuits, multi-chip modules (MCMs), hybrids, electronic modules, or devices using chip and wire designs in accordance with MIL-PRF-38534 are specified herein. Two product assurance classes consisting of military high reliability (device class Q) and space application (device class V) are reflected in the Part or Identification Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels are reflected in the PIN.

A.1.2 PIN. The PIN is as shown in the following example:



A.1.2.1 RHA designator. Device classes Q and V RHA identified die meet the MIL-PRF-38535 specified RHA levels. A dash (-) indicates a non-RHA die.

A.1.2.2 Device type(s). The device type(s) identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
02	LM193	Dual differential comparator
03	LM193	Dual differential comparator

A.1.2.3 Device class designator.

<u>Device class</u>	<u>Device requirements documentation</u>
Q or V	Certification and qualification to the die requirements of MIL-PRF-38535

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A.1.2.4 Die details. The die details designation is a unique letter which designates the die's physical dimensions, bonding pad location(s) and related electrical function(s), interface materials, and other assembly related information, for each product and variant supplied to this appendix.

A.1.2.4.1 Die physical dimensions.

<u>Die type</u>	<u>Figure number</u>
02, 03	A-1

A.1.2.4.2 Die bonding pad locations and electrical functions.

<u>Die type</u>	<u>Figure number</u>
02, 03	A-1

A.1.2.4.3 Interface materials.

<u>Die type</u>	<u>Figure number</u>
02, 03	A-1

A.1.2.4.4 Assembly related information.

<u>Die type</u>	<u>Figure number</u>
02, 03	A-1

A.1.3 Absolute maximum ratings. See paragraph 1.3 herein for details.

A.1.4 Recommended operating conditions. See paragraph 1.4 herein for details.

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A.2 APPLICABLE DOCUMENTS.

A.2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARD

MIL-STD-883 - Test Method Standard Microcircuits.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <http://quicksearch.dla.mil> or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

A.2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

A.3 REQUIREMENTS

A.3.1 Item requirements. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

A.3.2 Design, construction and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein and the manufacturer's QM plan for device classes Q and V.

A.3.2.1 Die physical dimensions. The die physical dimensions shall be as specified in A.1.2.4.1 and on figure A-1.

A.3.2.2 Die bonding pad locations and electrical functions. The die bonding pad locations and electrical functions shall be as specified in A.1.2.4.2 and on figure A-1.

A.3.2.3 Interface materials. The interface materials for the die shall be as specified in A.1.2.4.3 and on figure A-1.

A.3.2.4 Assembly related information. The assembly related information shall be as specified in A.1.2.4.4 and on figure A-1.

A.3.2.5 Radiation exposure circuit. The radiation exposure circuit shall be as defined in paragraph 3.2.3 herein.

A.3.3 Electrical performance characteristics and post-irradiation parameter limits. Unless otherwise specified herein, the electrical performance characteristics and post-irradiation parameter limits are as specified in table I of the body of this document.

A.3.4 Electrical test requirements. The wafer probe test requirements shall include functional and parametric testing sufficient to make the packaged die capable of meeting the electrical performance requirements in table I.

A.3.5 Marking. As a minimum, each unique lot of die, loaded in single or multiple stack of carriers, for shipment to a customer, shall be identified with the wafer lot number, the certification mark, the manufacturer's identification and the PIN listed in A.1.2 herein. The certification mark shall be a "QML" or "Q" as required by MIL-PRF-38535.

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A.3.6 Certification of compliance. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see A.6.4 herein). The certificate of compliance submitted to DLA Land and Maritime -VA prior to listing as an approved source of supply for this appendix shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and the requirements herein.

A.3.7 Certificate of conformance. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 shall be provided with each lot of microcircuit die delivered to this drawing.

A.4 VERIFICATION

A.4.1 Sampling and inspection. For device classes Q and V, die sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modifications in the QM plan shall not affect the form, fit, or function as described herein.

A.4.2 Screening. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and as defined in the manufacturer's QM plan. As a minimum, it shall consist of:

- a. Wafer lot acceptance for class V product using the criteria defined in MIL-STD-883, method 5007.
- b. 100% wafer probe (see paragraph A.3.4 herein).
- c. 100% internal visual inspection to the applicable class Q or V criteria defined in MIL-STD-883, method 2010 or the alternate procedures allowed in MIL-STD-883, method 5004.

A.4.3 Conformance inspection.

A.4.3.1 Group E inspection. Group E inspection is required only for parts intended to be identified as radiation assured (see A.3.5 herein). RHA levels for device classes Q and V shall be as specified in MIL-PRF-38535. End point electrical testing of packaged die shall be as specified in table IIA herein. Group E tests and conditions are as specified in paragraphs 4.4.4 and 4.4.4.1 herein.

A.5 DIE CARRIER

A.5.1 Die carrier requirements. The requirements for the die carrier shall be accordance with the manufacturer's QM plan or as specified in the purchase order by the acquiring activity. The die carrier shall provide adequate physical, mechanical and electrostatic protection.

A.6 NOTES

A.6.1 Intended use. Microcircuit die conforming to this drawing are intended for use in microcircuits built in accordance with MIL-PRF-38535 or MIL-PRF-38534 for government microcircuit applications (original equipment), design applications, and logistics purposes.

A.6.2 Comments. Comments on this appendix should be directed to DLA Land and Maritime -VA, Columbus, Ohio, 43218-3990 or telephone (614)-692-0540.

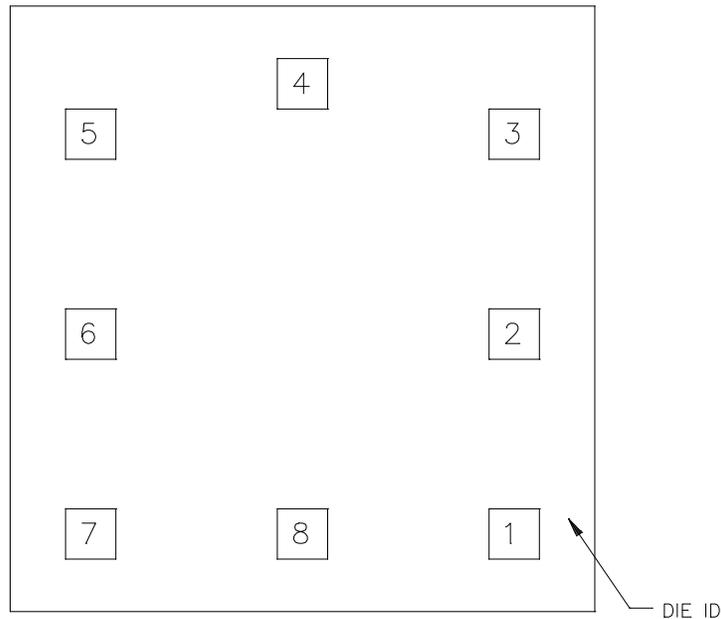
A.6.3 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

A.6.4 Sources of supply for device classes Q and V. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed within MIL-HDBK-103 and QML-38535 have submitted a certificate of compliance (see A.3.6 herein) to DLA Land and Maritime -VA and have agreed to this drawing.

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DIE LAYOUT (C-STEP)



Die bonding pad locations and electrical functions

Die physical dimensions.

Die size: 838.2 μm X 863.6 μm
33.0 mils X 34.0 mils

Die thickness: 330 μm

Minimum pitch: 263.00 μm

Interface materials.

Top metallization: AL 0.5% CU
Backside metallization: Bareback

Glassivation.

Type: Vapox over metal only (VOM only)
Thickness: 8 kÅ to 12 kÅ

Substrate: Silicon

Assembly related information.

Substrate potential: Floating
Special assembly instructions: None

FIGURE A-1. Die bonding pad locations and electrical functions.

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Die Bond Pad Coordinate Locations (C-Step) (Referenced to die center, coordinates in μm)						
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X	Y	
Output A	1	277	-314	92	X	92
Input A-	2	305	-42	92	X	92
Input A+	3	305	221	92	X	92
GND	4	-2	317	92	X	92
Input B+	5	-304	221	92	X	92
Input B-	6	-304	-42	92	X	92
Output B	7	-304	-314	92	X	92
V+	8	-38	-318	92	X	92

FIGURE A-1. Die bonding pad locations and electrical functions - continued.

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STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 16-01-28

Approved sources of supply for SMD 5962-94526 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DLA Land and Maritime-VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DLA Land and Maritime maintains an online database of all current sources of supply at <http://www.landandmaritime.dla.mil/Programs/Smcr/>.

Standard microcircuit drawing PIN <u>1/</u>	Vendor CAGE number	Vendor similar PIN <u>2/</u>
5962-9452601M2A	<u>3/</u>	LM193
5962-9452601QPA	01295	LM193JGB
5962-9452601Q2A	01295	LM193FKB
5962-9452602MPA	27014	LM193AJ/883
5962-9452602MGA	27014	LM193AH/883
5962-9452602VGA	<u>3/</u>	LM193AH-QMLV
5962-9452602VPA	27014	LM193AJ-QMLV
5962R9452602V9A	27014	LM193 MDR
5962R9452602VGA	27014	LM193AHRQMLV
5962R9452602VPA	27014	LM193AJRQMLV
5962R9452603V9A	27014	LM193 MDE
5962R9452603VGA	27014	LM193AHLQMLV
5962R9452603VPA	27014	LM193AJRLQMLV

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- 2/ **Caution.** Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 3/ Not available from an approved source of supply.

STANDARD MICROCIRCUIT DRAWING BULLETIN - Continued

DATE: 16-01-28

<u>Vendor CAGE number</u>	<u>Vendor name and address</u>
01295	Texas Instruments, Inc. Semiconductor Group 8505 Forest Ln. P.O. Box 660199 Dallas, TX 75243
27014	National Semiconductor Corporation 2900 Semiconductor Drive P.O. Box 58090 Santa Clara, CA 95052-8090

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.